

PINNACLE® CARRIERLESS WET STATION

System Overview

Designed for the most cutting-edge devices, the fully-automated, carrierless Pinnacle batch immersion wet station utilizes the most advanced wafer handling and process control subsystems to ensure the optimum process results for manufacturers of digital integrated circuits.

Substrate Size:	200 & 300 mm
Application compounds:	Si and others
Technology Markets:	Digital IC & Analog IC
Batch Size:	50 wafers

Processes

- Photoresist strip
- Pre-diffusion clean
- Nitride etch
- FEOL reclaim
- BEOL reclaim

Production Advantages

- Superior particle and metals performance
- Eliminates carrier-based defects—no shadowing or contact marks
- Rack and pinion style robot with absolute motor rotation encoding for precise positioning
- Single point facilities connection for water, nitrogen, and CDA
- Multi-tank plenum and modular compact design
- Real time tracking of chemicals, water, and gases
- Wafer Transfer System provides clean and dirty path (Pinnacle 300)

